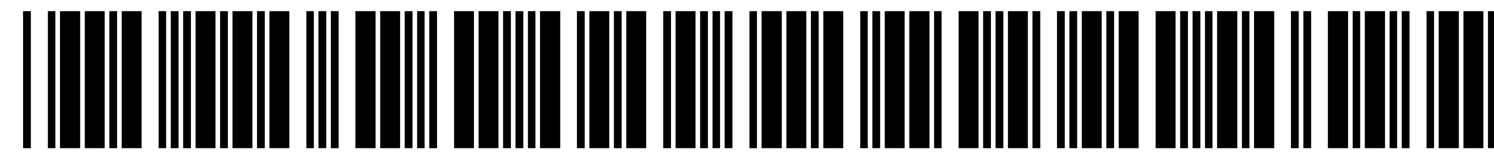

(12) **United States Design Patent** (10) **Patent No.: US D972,516 S**
Hara (45) **Date of Patent:** ** **Dec. 13, 2022**

(54) **SEMICONDUCTOR MODULE**

(71) Applicant: **ROHM CO., LTD.**, Kyoto (JP)

(72) Inventor: **Hideo Hara**, Kyoto (JP)

(73) Assignee: **ROHM CO., LTD.**, Kyoto (JP)

(**) Term: **15 Years**

(21) Appl. No.: **29/743,417**

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(30) **Foreign Application Priority Data**

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(51) **LOC (13) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
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(Continued)

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Primary Examiner — Shawn T Gingrich
(74) *Attorney, Agent, or Firm* — Hamre, Schumann, Mueller & Larson, P.C.

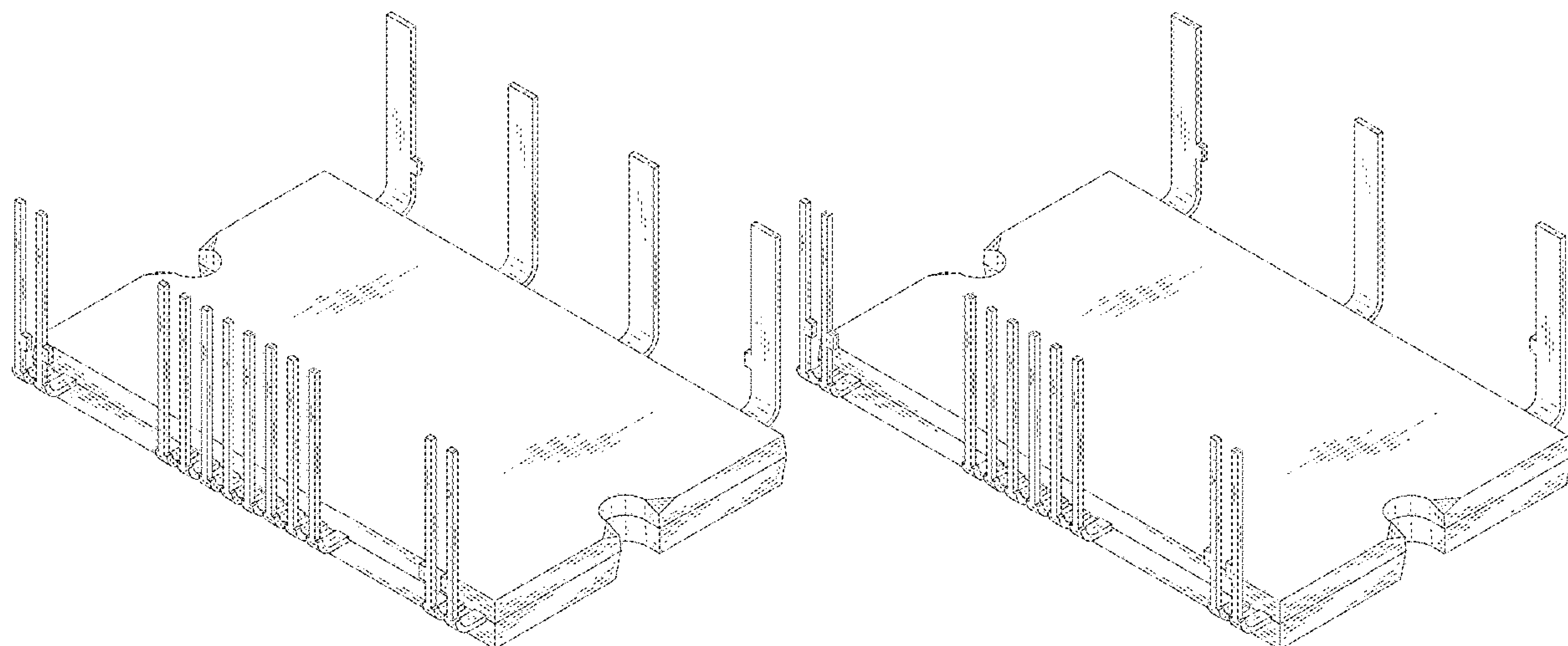
(57) **CLAIM**

The ornamental design for a semiconductor module, as shown and described.

DESCRIPTION

FIG. **1** is a front, top and right side perspective view of a first embodiment of a semiconductor module showing my new design;
FIG. **2** is a rear, bottom and left side perspective view thereof;
FIG. **3** is a front view thereof;
FIG. **4** is a rear view thereof;
FIG. **5** is a top plan view thereof;
FIG. **6** is a bottom plan view thereof;
FIG. **7** is a right side view thereof, the left side view being a mirror image of FIG. **7**;
FIG. **8** is a front, top and right side perspective view of a second embodiment of a semiconductor module showing my new design;
FIG. **9** is a rear, bottom and left side perspective view thereof;
FIG. **10** is a front view thereof;
FIG. **11** is a rear view thereof;
FIG. **12** is a top plan view thereof;
FIG. **13** is a bottom plan view thereof; and,
FIG. **14** is a right side view thereof, the left side view being a mirror image of FIG. **14**.
The broken lines illustrate portions of the semiconductor module that form no part of the claimed design. The dash-dotted lines denote the boundary of the claim and form no part of the claimed design. The oblique line shading shown in the drawings indicates transparent parts.

1 Claim, 14 Drawing Sheets



(30) **Foreign Application Priority Data**

Jan. 28, 2020 (JP) .... 2020-001383 D
Jan. 28, 2020 (JP) .... 2020-001384 D

(58) **Field of Classification Search**
CPC .. H05K 1/18; H05K 7/00; H05K 7/20; H02M 7/00; H01L 25/07; H01L 25/16; H01L 25/18; H01L 23/00; H01L 23/31
See application file for complete search history.

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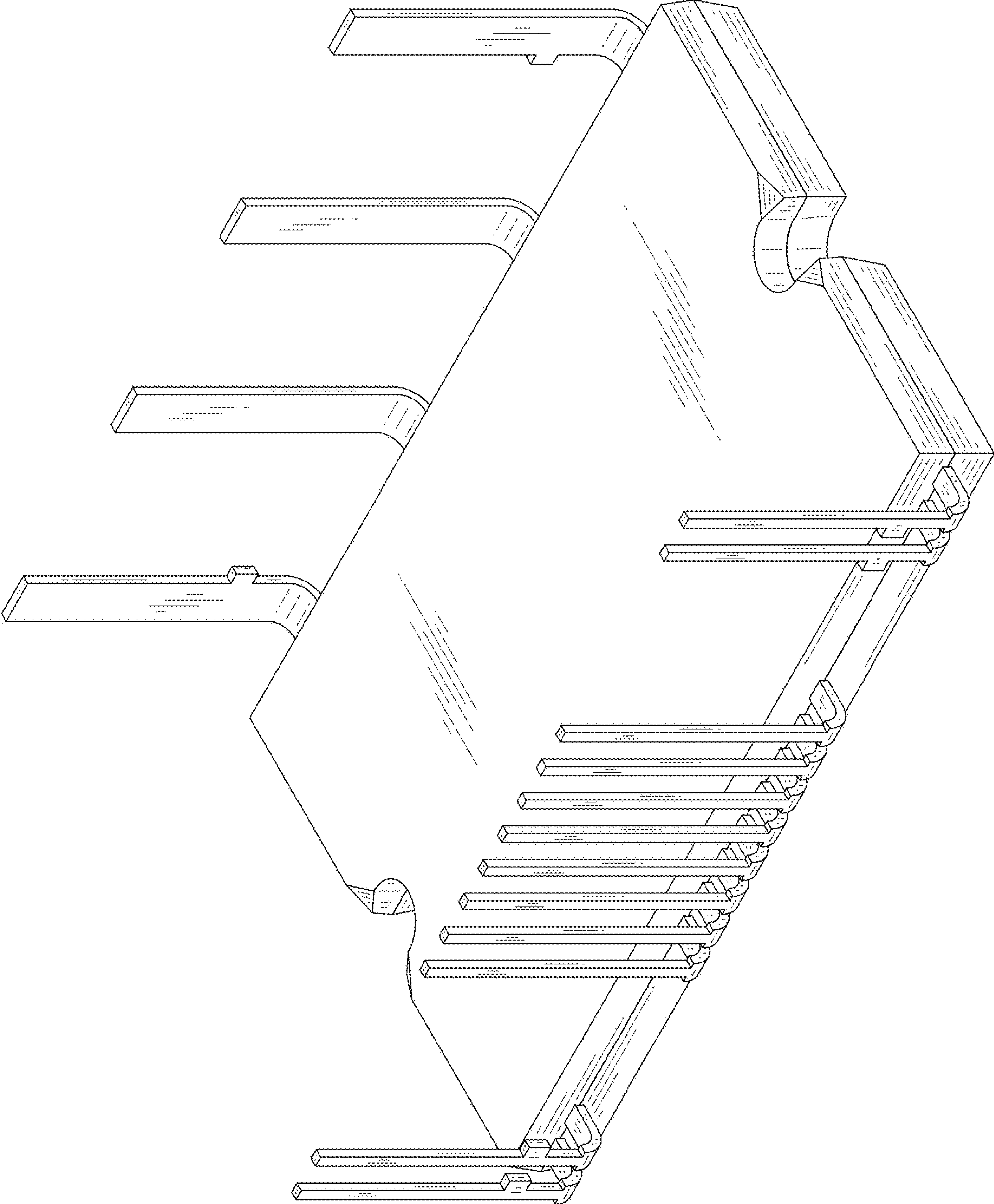

FIG.1

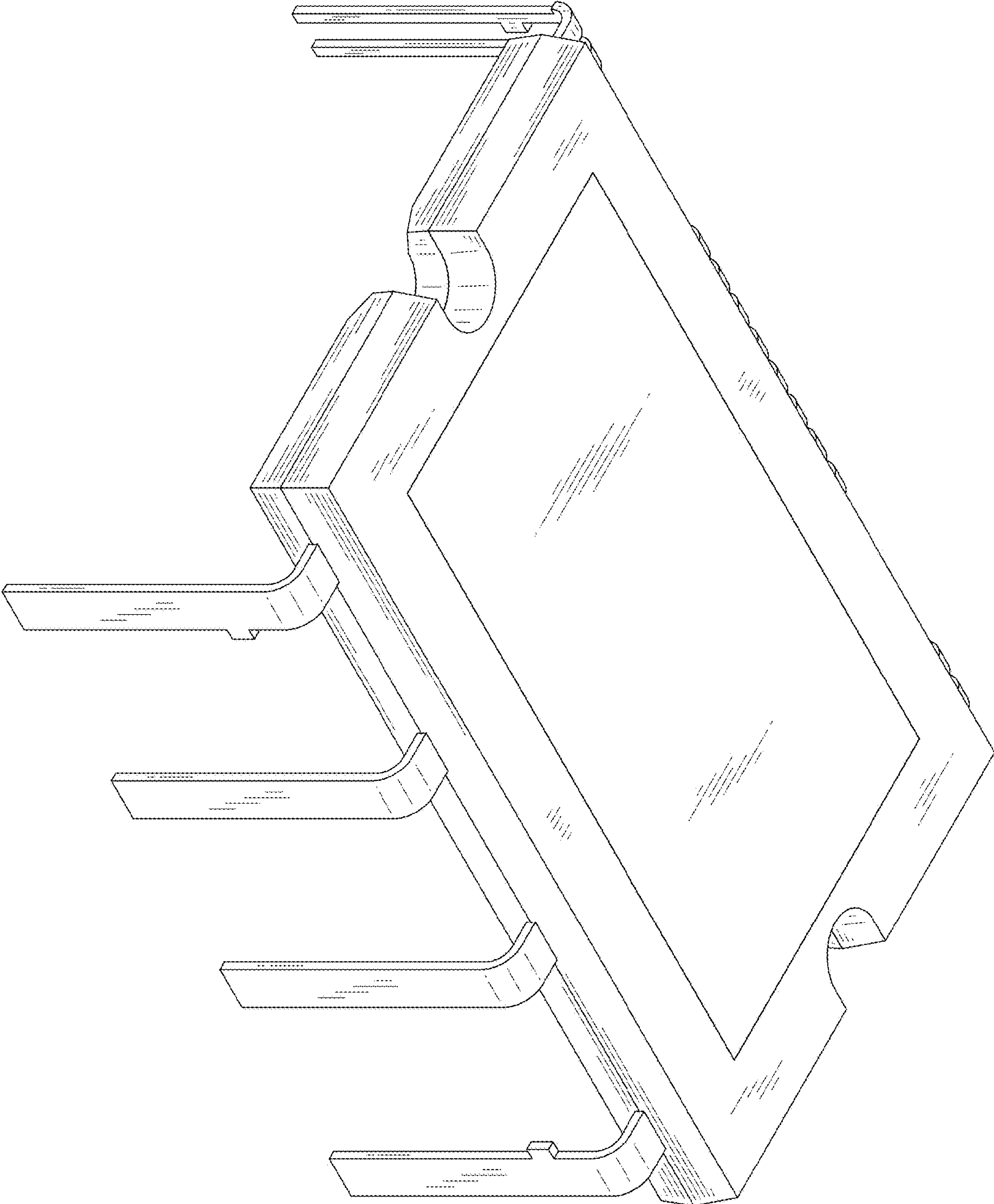

FIG.2

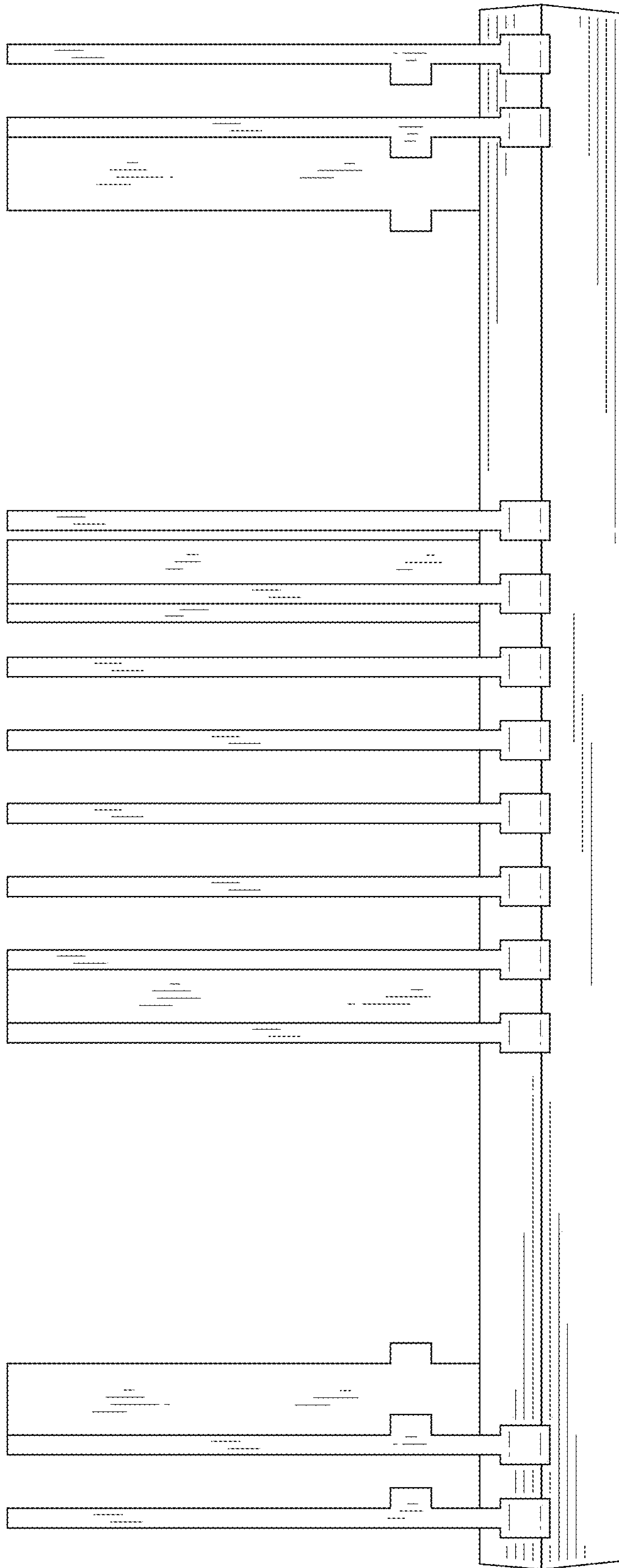

FIG.3

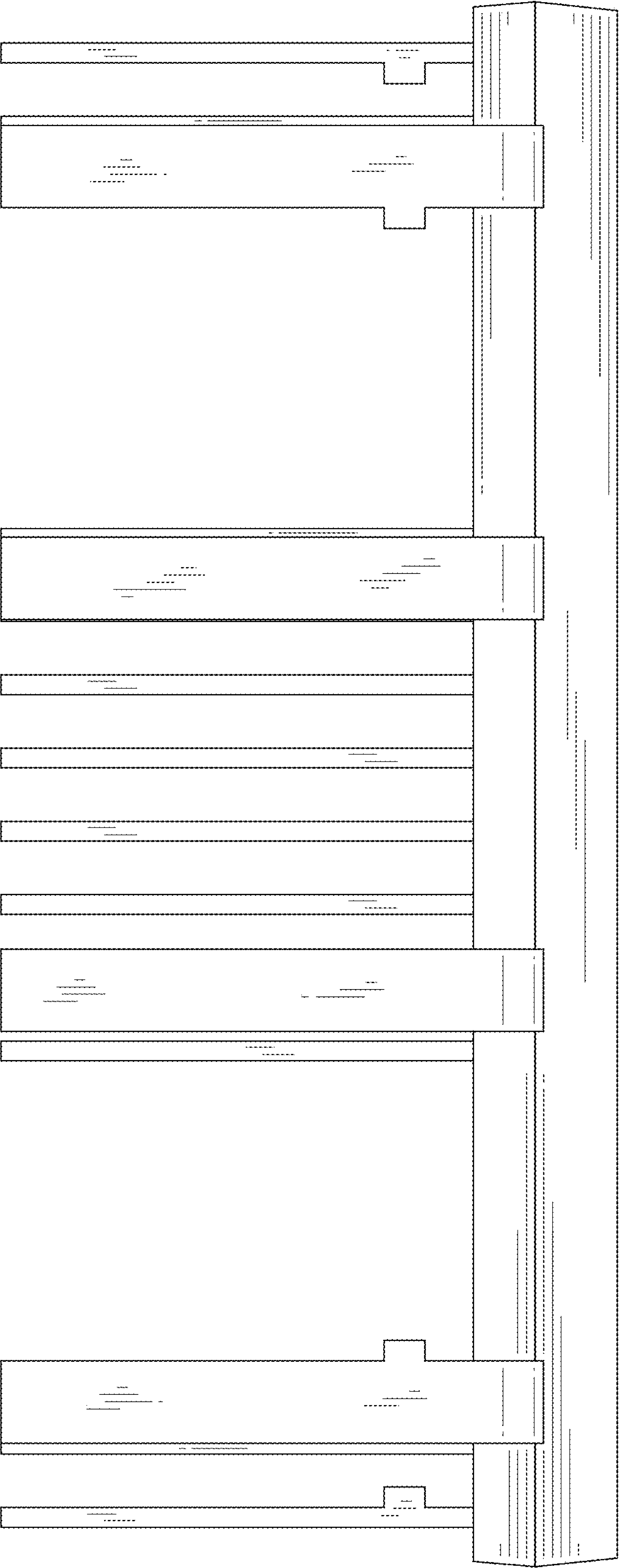

FIG.4

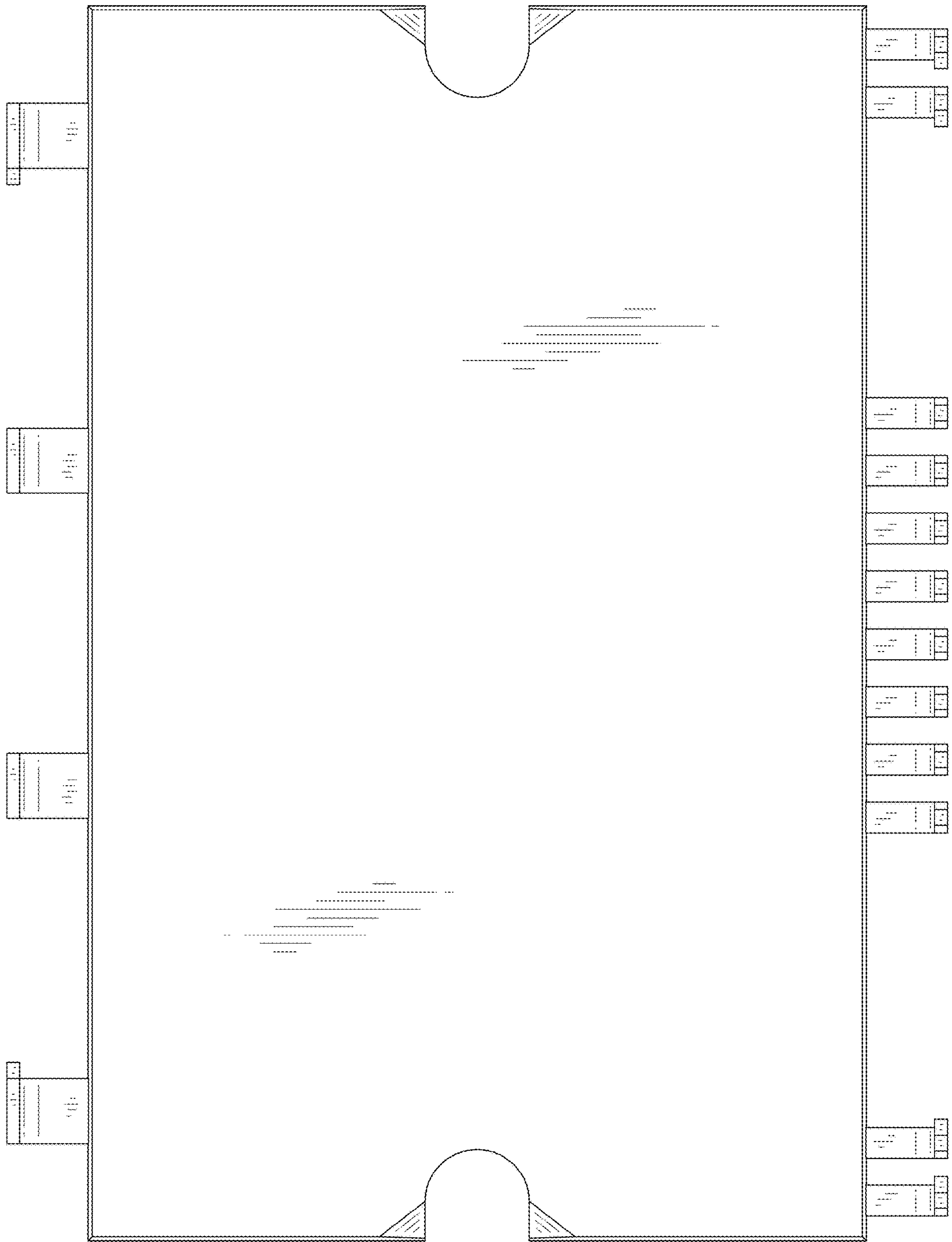

FIG.5

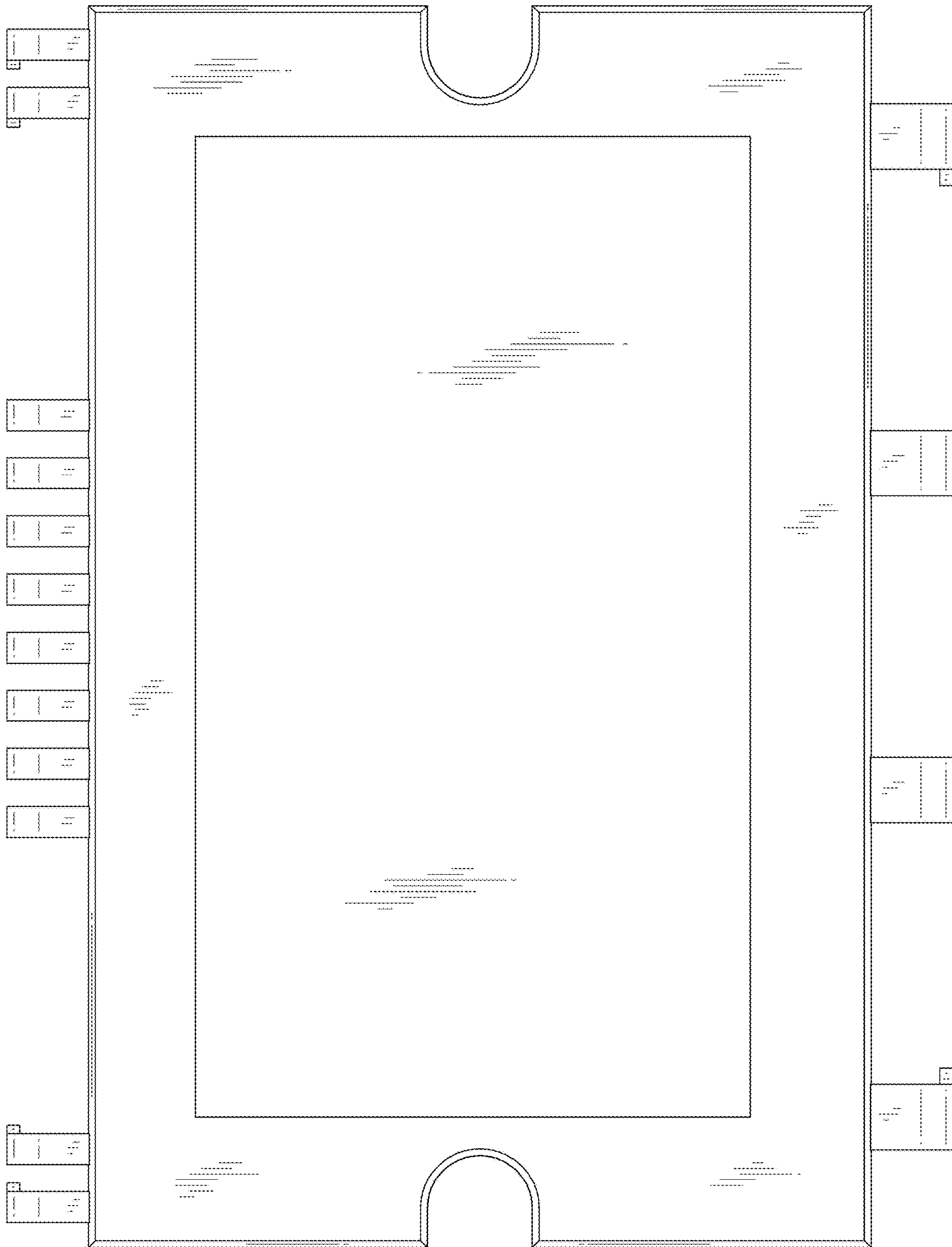

FIG.6

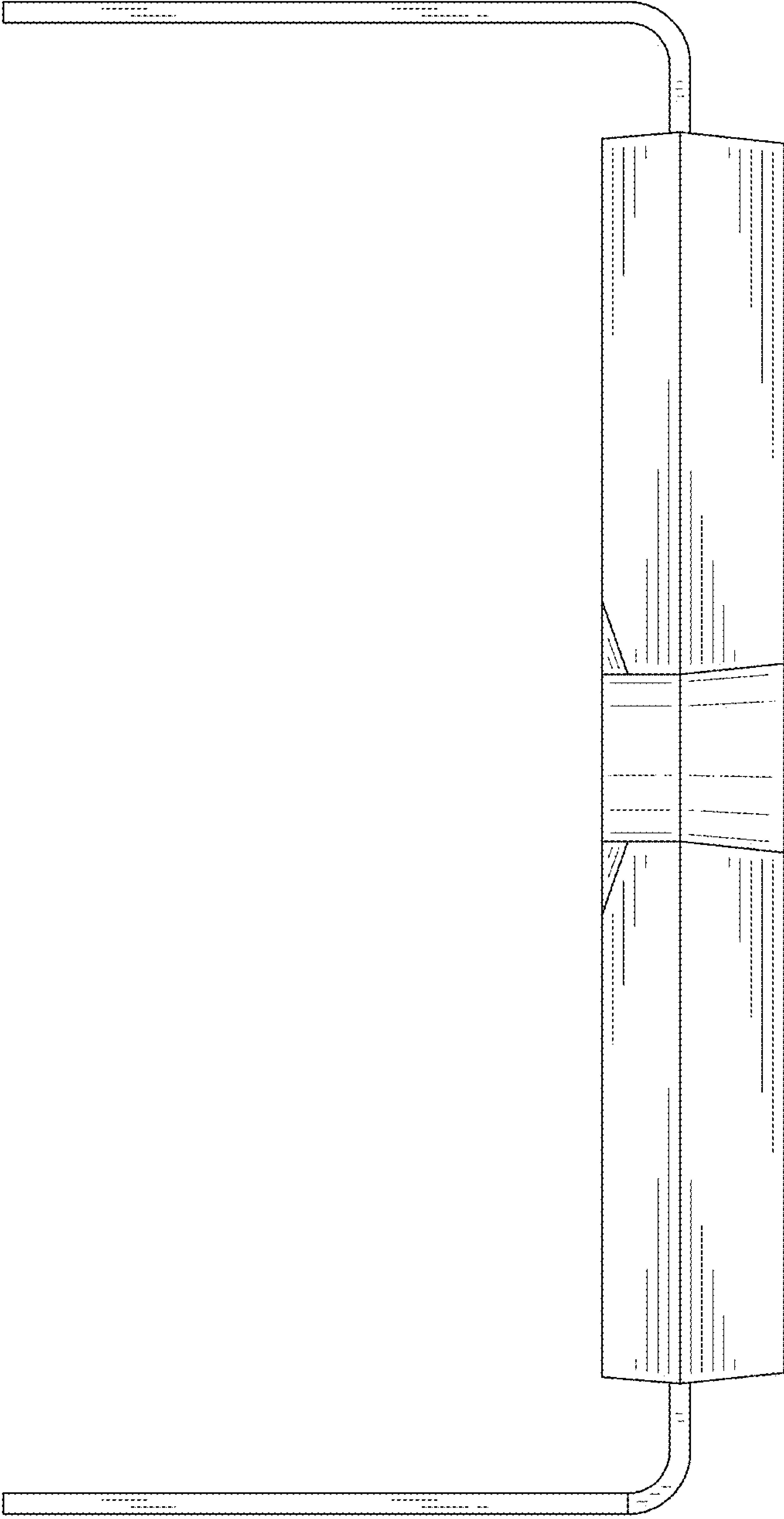

FIG.7

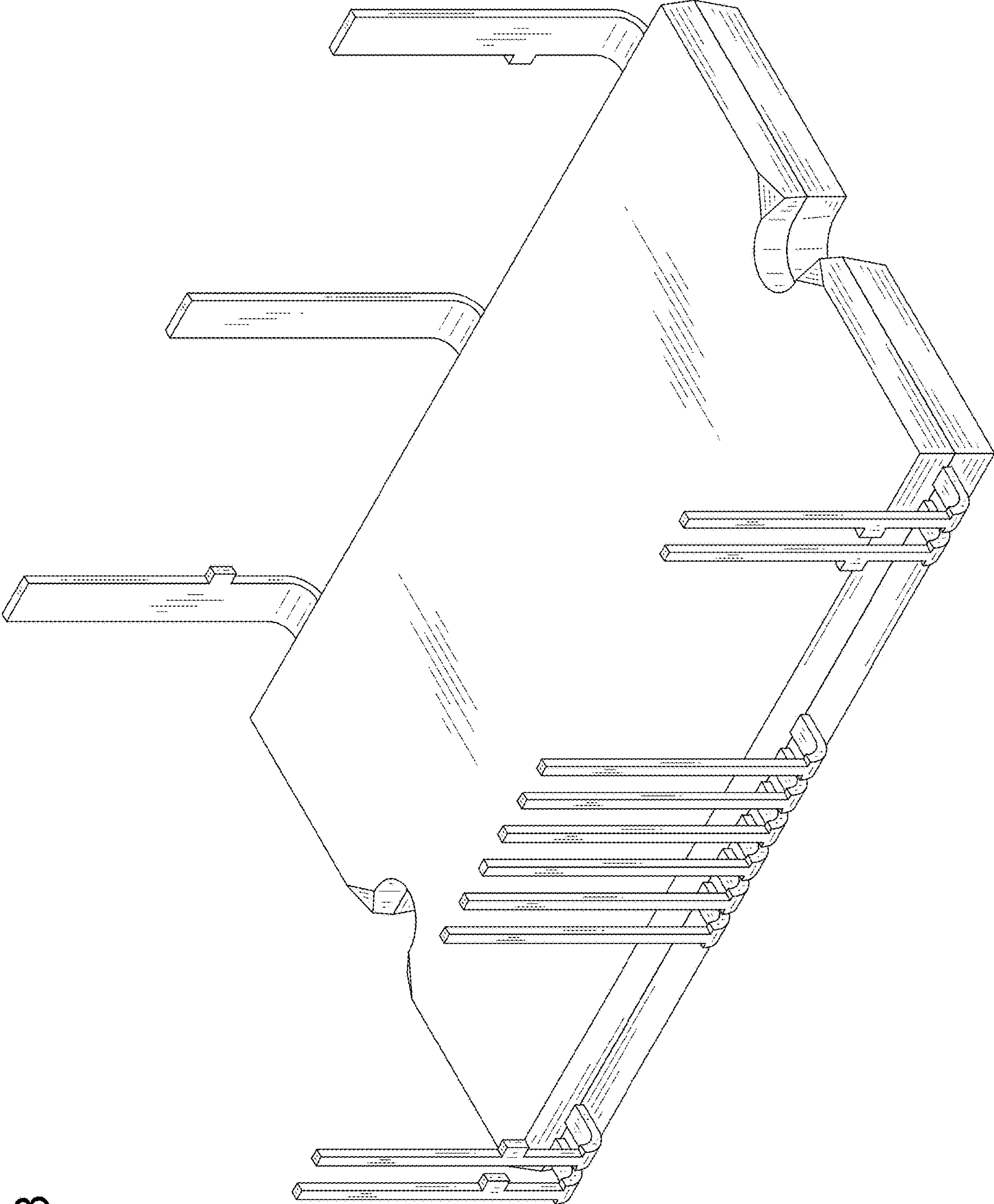

FIG.8

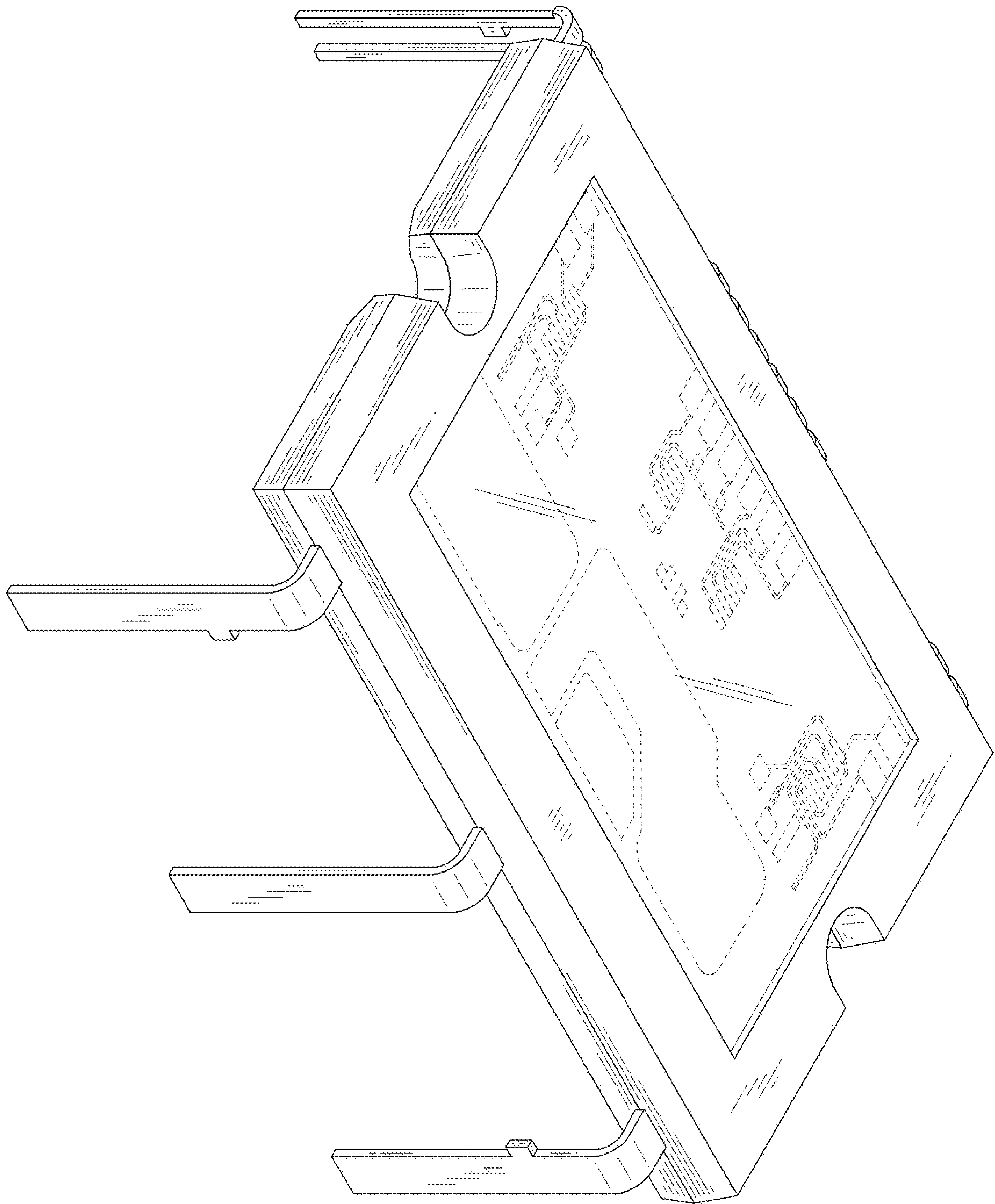

FIG.9

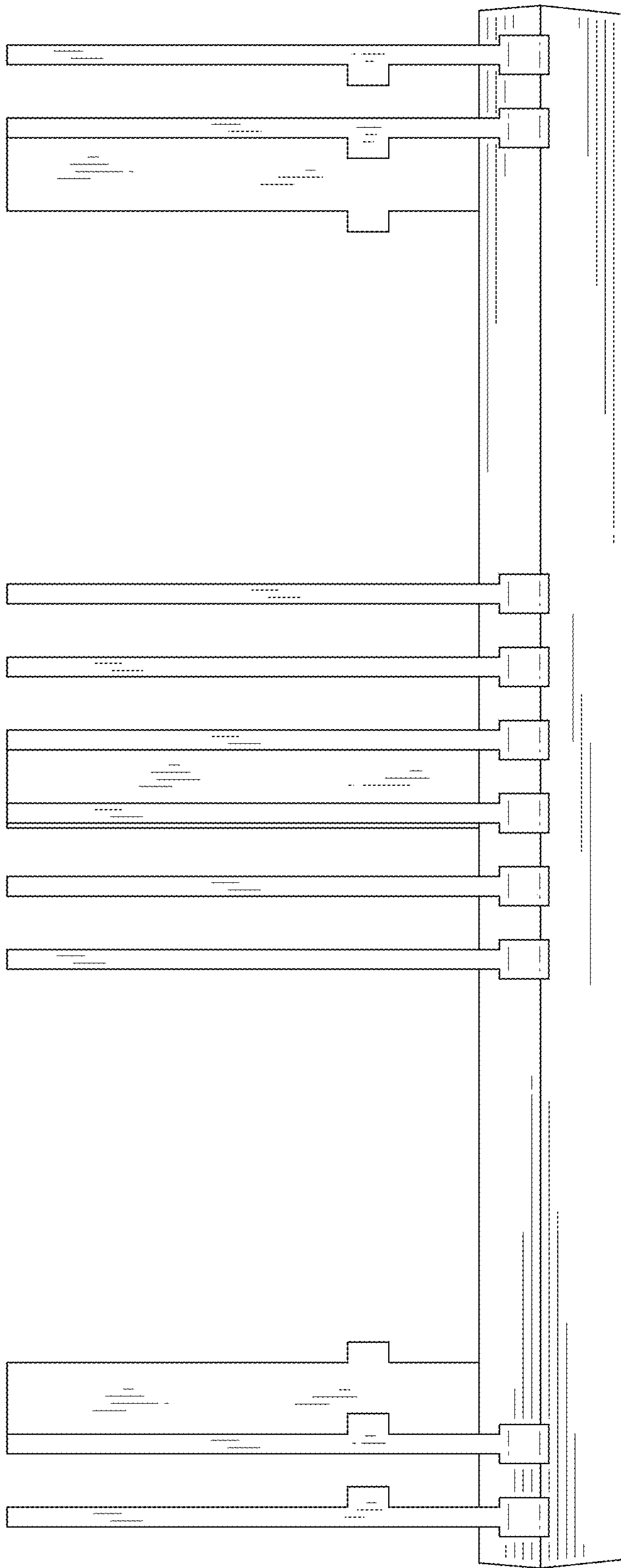

FIG.10

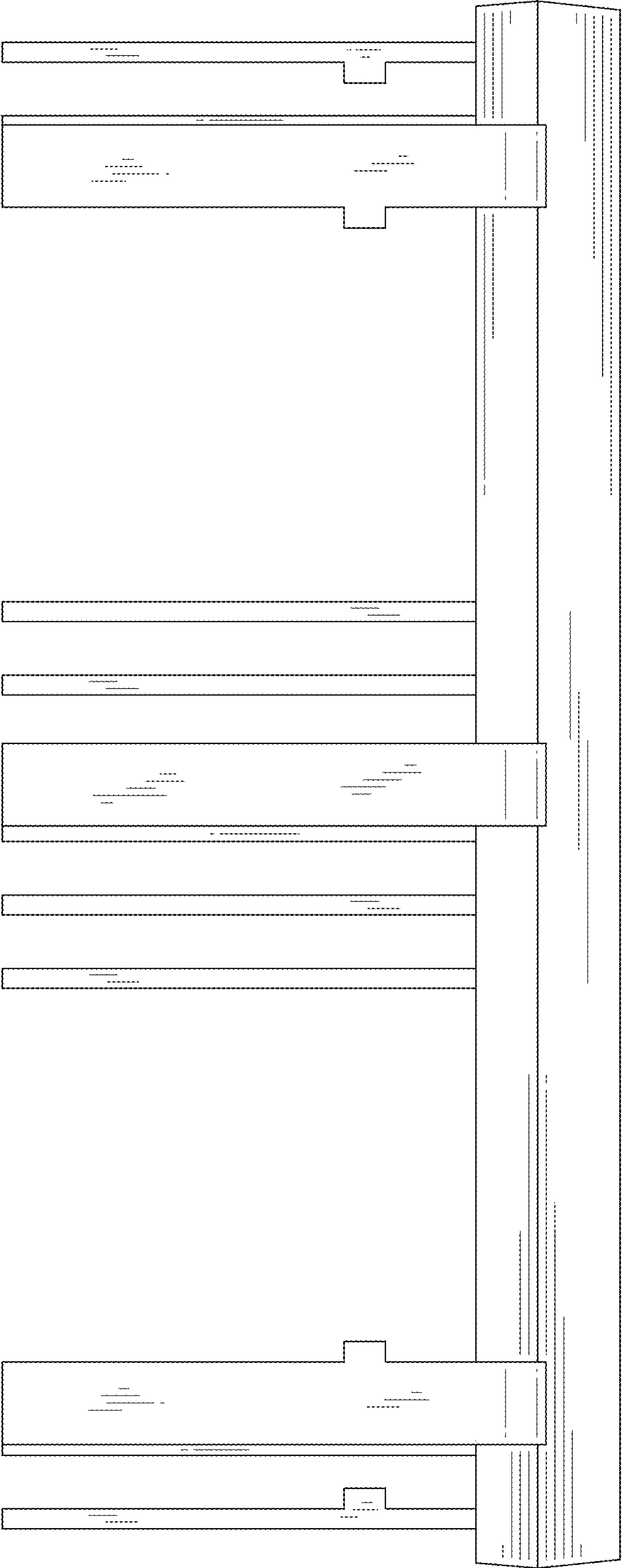

FIG.11

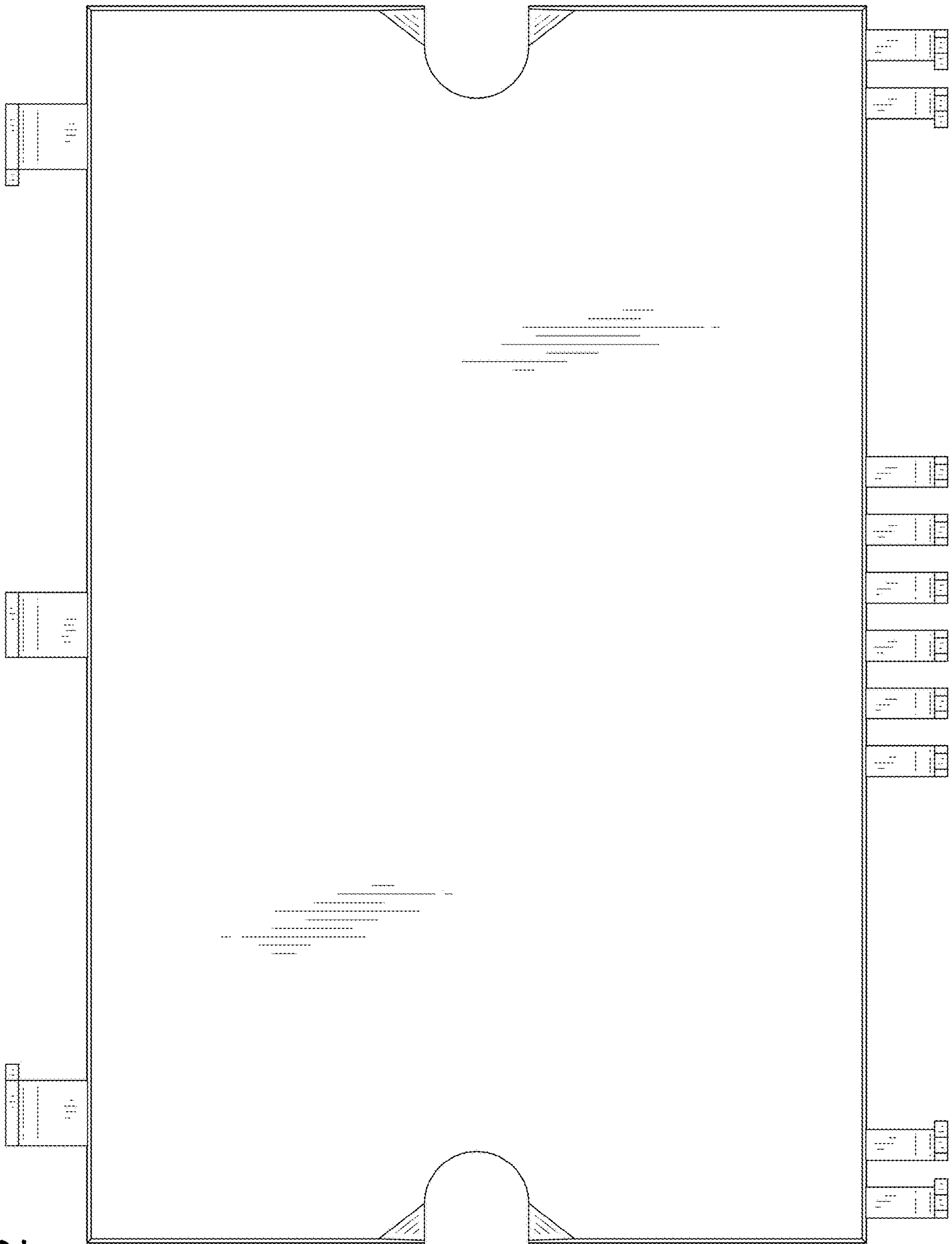

FIG.12

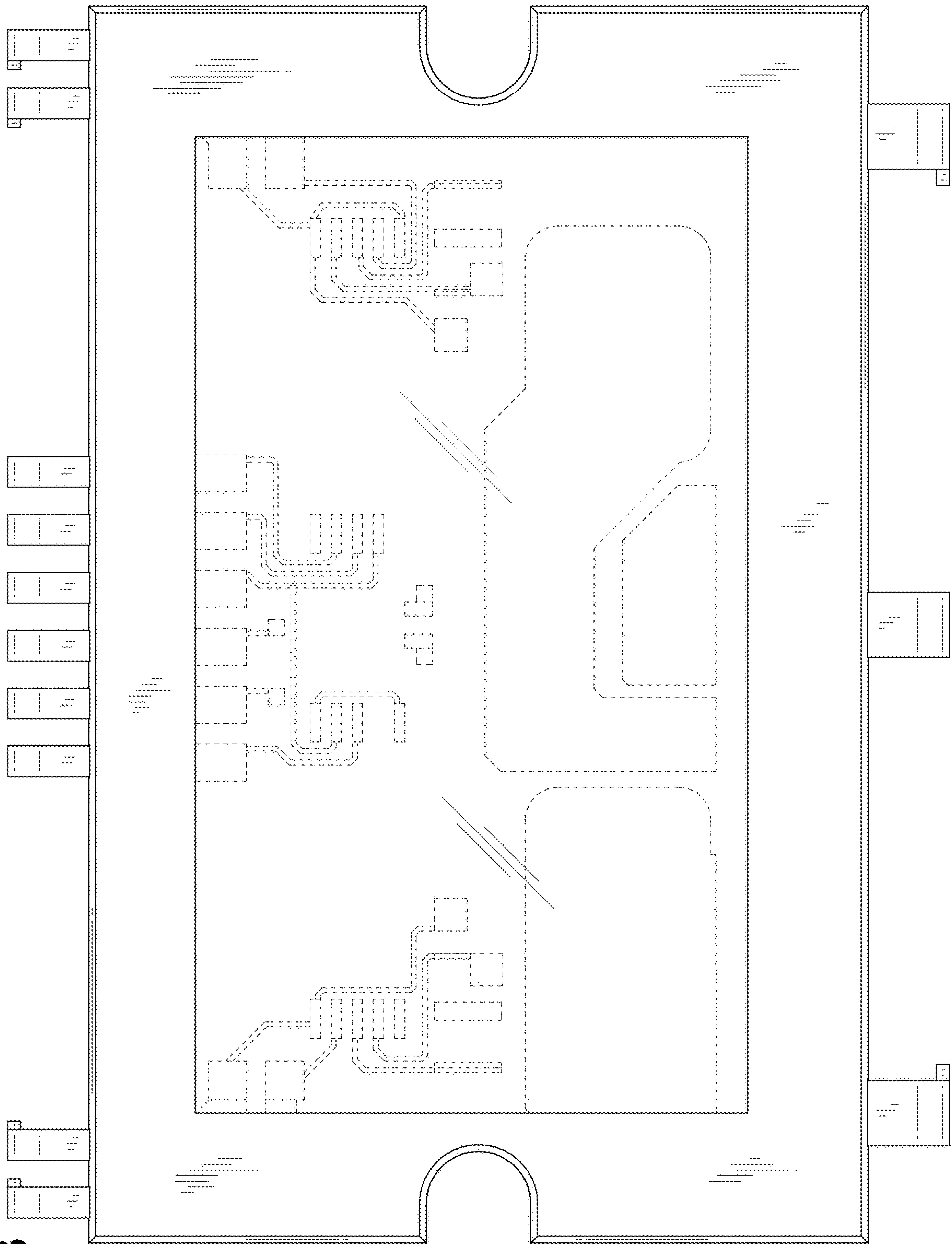

FIG.13

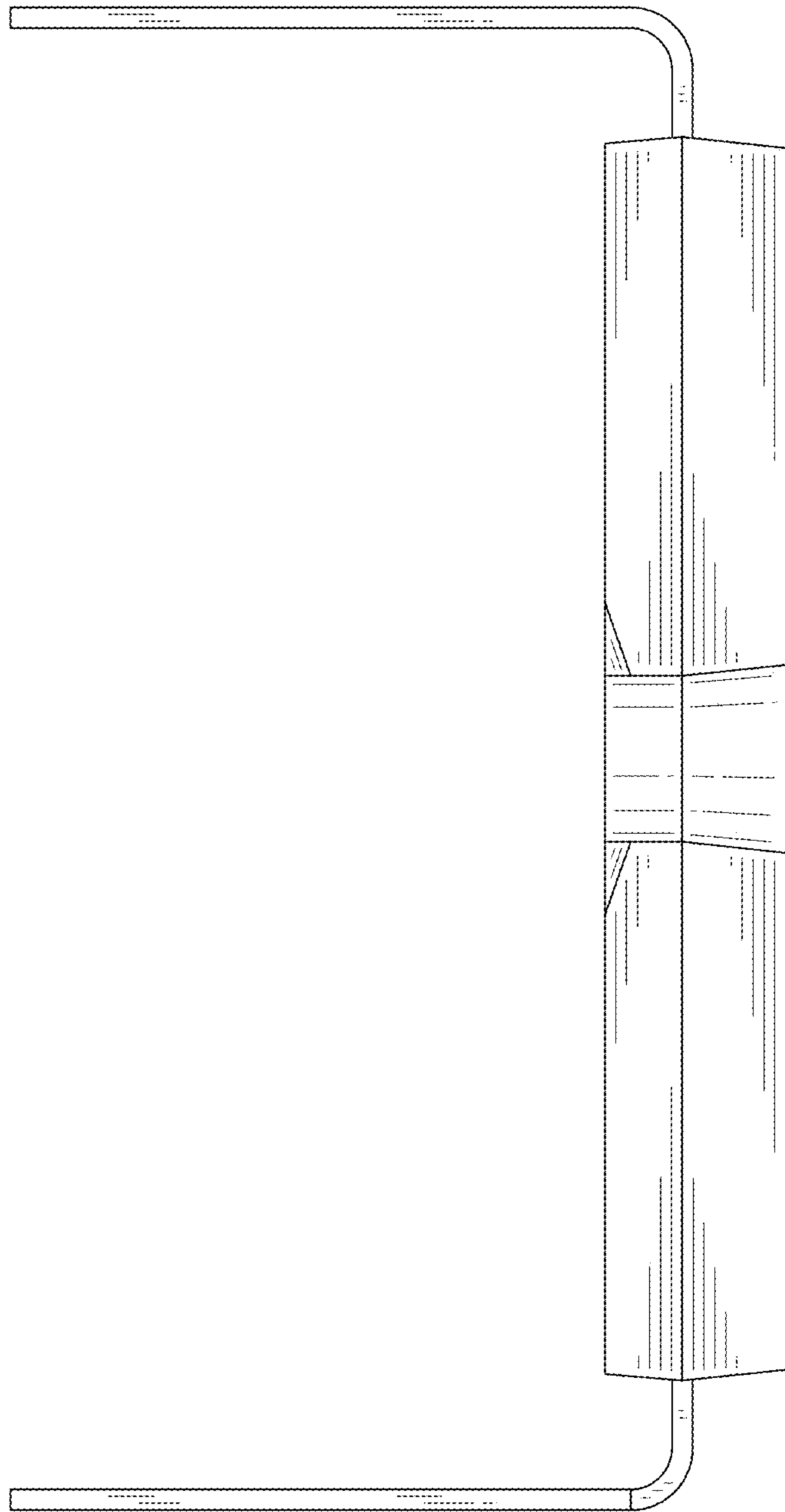

FIG.14